Final Product Change Notification

201509016F02

Issue Date: 10-Feb-2016
Effective Date: 24-May-2016

Here’s your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online

Management Summary

Revised change notice for microcontroller products LPC18x0, LPC18Sx0, LPC43x0 and LPC43Sx0 will be sourced from the new product version Rev "D".
Currently released version is Rev. "C".

Change Category

[ ] Wafer Fab process
[ ] Wafer Fab materials
[ ] Wafer Fab location
[ ] Assembly Process
[ ] Assembly Materials
[ ] Assembly Location
[ ] Product Marking
[ ] Electrical spec./Test coverage
[ ] Test Location
[X] Design
[ ] Mechanical Specification
[ ] Packing/Shipping/Labeling

LPC18x0, LPC18Sx0, LPC43x0 and LPC43Sx0 change from Rev "C" to Rev "D"

Details of this Change

Microcontroller products LPC18x0, LPC18Sx0, LPC43x0 and LPC43Sx0 will be sourced from the new product version Rev "D".
Currently released version is Rev "C".

- No wafer fab location or process change.

- This change resolves the following known functional deviation as documented in the device errata:

OTP.2 - Repeated power cycling of the device may cause erroneous programing of the OTP banks.

- The change will NOT include changes to the boot ROM code to resolve additional errata items as previously stated in FPCN 201509016F01 (OTP.1,USBROM.2, USBROM.3, ISP.1, ISP.2). The same boot ROM version as in rev C will be used to eliminate any possible compatibility issues between rev C and rev D.

- device functionality does not change.

Why do we Implement this Change

To resolve known functional deviation OTP.2 as documented in the errata sheets.

Identification of Affected Products

Top side marking
The last 2 characters of the last line change from "0C" to "2D"

Product Availability

Sample Information
Samples are available from 07-Mar-2016
Production
Planned first shipment 24-May-2016

Impact

Although the new product revision is expected to be electrically identical it is recommended that customers fully characterize the change in their applications.
Data Sheet Revision
No impact to existing datasheet
Disposition of Old Products
Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 11-Mar-2016.

Remarks

For sample availability please contact your local distributor or NXP Sales.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	Tim Camenzind
Position	Senior Quality Engineer
e-mail address	tim.camenzind@nxp.com

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NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands